

Amendments to the Specification

Please replace the paragraph beginning on page 1, line 23, with the following amended paragraph:

For meeting this necessity, currently, the printed circuit board is densified by fabricating a multi layer (printed circuit) board formed with a plurality of layers. In the multi layer board 1, open through holes 1d and via blind holes 1c may be ~~form~~ formed in the board wherein a conductive layer 1e is coated in the holes 1c and 1d to electrically interconnect circuit patterns 1a and 1b of one or more an inner layers and/or the surface layers, with reference to Figure 1A.

Please replace the paragraph beginning on page 14, line 6, with the following paragraph:

The hole plugging method of the printed circuit board in accordance with the present invention will be described with reference to ~~Figures 6~~ Figures 6 and 7.